

## Publikationen

Werner Bogner, Johannes Jakob, R. Weigel, Franz Xaver Röhl, Stefan Zorn (2019): Bare die connections via aerosol jet technology for millimeter wave applications. In: International Journal of Microwave and Wireless Technologies, vol. 11, no. Special Issue 5-6 (EuMW 2018 Special Issue (Part I)) [June], pp. 441-446. DOI: 10.1017/S1759078719000114.

Werner Bogner, Franz Xaver Röhl, Felix Sepaintner, Stefan Zorn, Andreas Scharl (2019): Simulation and Manufacturing of Low Loss PCB Structures with Additional Electromagnetic Field in Air. In: Proceedings of the IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes (IMWS-AMP) [July 16-18, 2019; Bochum].

Werner Bogner, Johannes Jakob, R. Sammer, Franz Xaver Röhl, Stefan Zorn (2019): WR12 to planar transmission line transition on organic substrate. In: Proceedings of the 49th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2019 (September 29-October 4, 2019; Paris, France).

Werner Bogner, Johannes Jakob, R. Weigel, Franz Xaver Röhl, Stefan Zorn (2018): Bare Die Connections via Aerosol Jet Technology for Millimeter Wave Applications. In: Proceedings of the 48th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2018 (September 24-28, 2018; Madrid, Spain).

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- Werner Bogner, Johannes Jakob, R. Sammer, Franz Xaver Röhr, Stefan Zorn: WR12 to planar transmission line transition on organic substrate. Invited Talk. In: 49th European Microwave Conference (EuMC), Paris, France.
- Werner Bogner, Franz Xaver Röhr, Felix Sepaintner, Stefan Zorn, Andreas Scharl: Simulation and Manufacturing of Low Loss PCB Structures with Additional Electromagnetic Field in Air. Invited Talk. In: IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes (IMWS-AMP), Bochum.
- Werner Bogner, Johannes Jakob, Siegfried Hildebrand, Franz Xaver Röhr, Stefan Zorn: Projekt NePUMuk (Neue digitale Produktions- und Mikrostrukturierungstechnologien für Anwendungen bis 80 GHz). Projektbericht.
- M. Nafría, Manuel Bogner, Tobias Berthold, Günther Benstetter, R. Rodríguez, Werner Frammelsberger: Protective nanometer films for reliable Cu-Cu connections. Invited Talk. In: IEEE International Reliability Physics Symposium (IRPS), San Francisco, CA, USA.
- Werner Bogner, et al.: 40Gbit/s SiGe bipolar chipset for terabit optical networks. In: EE Seminar on High Performance Semiconductor Devices and Circuits for Communication, London, Great Britain.
- Werner Bogner, R. Roskosch, H. Tischer, et al., T. Kerksenbrock: W-Band sensor module in flip-chip technology. In: International IEEE MTT/AP Workshop on MMIC Design, Packaging and System Applications, Freiburg.